

6. A solder according to claim 1, further comprising an adjuvant for promoting rapid or more complete tissue healing.

A3 Sub B3 7. A solder according to claim 6 wherein the adjuvant is a growth factor, a sodium hyaluronate, a hormone or an anti-coagulant.

8. A solder according to claim 1, further comprising a material for improving the strength of the solder.

10. A kit comprising a solder according to any one of claims 1 to 9.

A4 Sub B4 11. A method of preparing a biomolecular solder, the method comprising the following steps:

- (a) forming a substantially solid composition comprising biomolecules and a solvent;
- (b) denaturing the biomolecules in the composition; and
- (c) drying the composition to form a solder; wherein in step (b), the biomolecules are denatured so that, in use, the solubility of the solder is reduced.

A5 Sub B7 15. A method according to claim 14 wherein the composition is heated in a hot liquid bath or in pressurized steam.

A6 17. A method according to claim 11 wherein in step (a), the substantially solid composition is formed by mixing the biomolecules with the solvent in amounts which are sufficient to allow the substantially solid composition to form.

18. A method according to claim 17 wherein the biomolecules and the solvent are mixed in amounts of up to 80%w/w and up to 60%w/w, respectively.

A6 Sub 39 19. A method according to claim 11 wherein in step (a), a dye for improving energy deposition into the solder is added to the substantially solid composition.

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A7 Sub 11 21. A method according to claim 20 wherein the dye is mixed with the solvent prior to mixing the solvent with the biomolecules.

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22. A method according to claim 11 wherein in step (c), the composition to form the solder is dried to remove all of the solvent from the solder.

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A8 Sub 13 25. A method according to claim 24 wherein the structure is a mesh, a stiffener or a graft material.

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A9 Sub 15 27. A method of repairing a biological tissue, the method comprising the following steps:

- (a) applying a solder according to claim 1 to the site of a tissue to be repaired; and
- (b) exposing the solder to energy for a time sufficient to allow the solder to bond to the tissue to be repaired. --